Z-PACK | Z-PACK TinMan

TE Internal #: 1934272-1

120 Position High Speed Backplane Connector, 15 Row, 8 Column, PCB Mount Header, Vertical, Partially Shrouded, Z-PACK TinMan

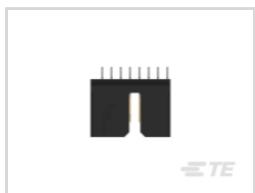
View on TE.com >



Connectors > PCB Connectors > Backplane Connectors > High Speed Backplane Connectors











Number of Positions: 120

Row-to-Row Spacing: 2.5 mm [.098 in]

Mating Alignment: With

Mating Alignment Type: Guide Slot

Number of Rows: 15

Features

Product Type Features

| Signal Arrangement | Differential |
|-----------------------------------|-----------------------|
| Connector & Contact Terminates To | Printed Circuit Board |
| Connector System | Board-to-Board |
| Backplane Module Type | Left |
| PCB Connector Type | PCB Mount Header |
| Shroud Style | Partially Shrouded |
| Configuration Features | |
| Number of Pairs | 40 |

| | · · | |
|---------------------|-----|--|
| Number of Positions | 120 | |
| | | |

Number of Rows 15 8



| PCB Mount Orientation | Vertical |
|---|--------------------------|
| Electrical Characteristics | |
| Operating Voltage | 250 VAC |
| Impedance | 100 Ω |
| Signal Characteristics | |
| Data Rate | 10 Gb/s |
| Differential Impedance | 100 Ω |
| Number of Differential Pairs per Column | 5 |
| Body Features | |
| Primary Product Color | Black |
| Contact Features | |
| PCB Contact Termination Area Plating Material Finish | Matte |
| Contact Mating Area Plating Material Thickness | .76 μm[29.92 μin] |
| PCB Contact Termination Area Plating Material Thickness | .5 μm[20 μin] |
| Contact Shape & Form | Rectangular |
| Contact Mating Area Plating Material | Gold (Au) |
| Contact Mating Area Length | 6 mm[.236 in] |
| Contact Base Material | Phosphor Bronze |
| PCB Contact Termination Area Plating Material | Tin |
| Contact Type | Pin |
| Contact Current Rating (Max) | .5 A |
| Termination Features | |
| Termination Method to PCB | Through Hole - Press-Fit |
| Termination Post & Tail Length | 2.5 mm[.098 in] |
| Mechanical Attachment | |
| Guide Hardware | Without |
| PCB Mount Retention | With |
| Mating Retention | Without |
| PCB Mount Retention Type | Action/Compliant Tail |
| PCB Mount Alignment | Without |
| Mating Alignment | With |
| Mating Alignment Type | Guide Slot |
| | |



| Connector Mounting Type | Board Mount |
|---|---------------------------|
| Housing Features | |
| Number of Shrouded Sides | 2 |
| End Wall Location | Left |
| Housing Material | LCP |
| Centerline (Pitch) | 1.9 mm[.075 in] |
| Dimensions | |
| Connector Width | 24.4 mm |
| Connector Height | 11.8 mm |
| PCB Hole Diameter | .47 mm |
| Connector Length | 15.35 mm |
| Row-to-Row Spacing | 2.5 mm[.098 in] |
| Usage Conditions | |
| Operating Temperature Range | -65 – 90 °C[-85 – 194 °F] |
| Operation/Application | |
| Circuit Application | Signal |
| Industry Standards | |
| Compatible With Agency/Standards Products | UL |
| UL Flammability Rating | UL 94V-0 |
| Compatible With Approved Standards Products | UL E28476 |
| Packaging Features | |
| Packaging Method | Box & Tube, Tube |

Product Compliance

For compliance documentation, visit the product page on TE.com>

| EU RoHS Directive 2011/65/EU | Compliant |
|---|---|
| EU ELV Directive 2000/53/EC | Compliant |
| China RoHS 2 Directive MIIT Order No 32, 2016 | No Restricted Materials Above Threshold |
| EU REACH Regulation (EC) No. 1907/2006 | Current ECHA Candidate List: JAN 2025 (247) Candidate List Declared Against: JAN 2025 (247) Does not contain REACH SVHC |
| | |



| Halogen Content | Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free |
|---------------------------|---|
| Solder Process Capability | Not applicable for solder process capability |

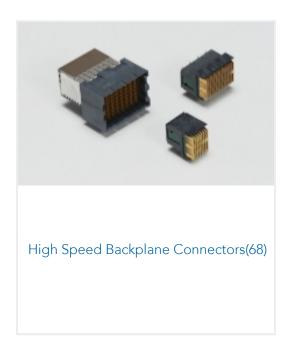
Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts



Also in the Series | Z-PACK TinMan



Customers Also Bought

















Documents

Product Drawings

Tin Man Header Assy 5x8 left

English

CAD Files

Customer View Model

ENG_CVM_1934272-1_B.3d_igs.zip

English

Customer View Model

ENG_CVM_1934272-1_B.3d_stp.zip

English

Customer View Model

ENG_CVM_1934272-1_B.2d_dxf.zip

English

3D PDF

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Datasheets & Catalog Pages

High Speed Backplane Connectors catalog - Z-PACK TinMan High Speed, High Density Backplane Connector

English

Z-PACK TinMan High Speed High Density Backplane Connector Catalog 5-1773447-9

English

Product Specifications

Application Specification

English

120 Position High Speed Backplane Connector, 15 Row, 8 Column, PCB Mount Header, Vertical, Partially Shrouded, Z-PACK TinMan

